

TWEPP 2011 Topical Workshop on Electronics for Particle Physics

Thursday, September 29, 2011

A5b - Packaging and Interconnects - Radiation tolerant components and systems - Rom EI 7 (11:00 AM - 12:40 PM)

-Conveners: Jorgen Christiansen

time	[id] title	presenter
11:00	[57] SLID-ICV interconnection technology for the ATLAS pixel upgrade at SLHC	Dr MACCHIOLO, Anna
11:25	[41] Characterization of a commercial 65nm CMOS technology for SLHC applications.	Dr BONACINI, Sandro
11:50	[39] Radiation Tolerance of Readout Electronics for Belle II	Dr HIGUCHI, Takeo
12:15	[18] nanoFIP: a radiation tolerant FPGA-based WorldFIP agent	Ms GOUSIOU, Evangelia